

CMLDM8120
CMLDM8120G*

SURFACE MOUNT
P-CHANNEL
ENHANCEMENT-MODE
SILICON MOSFET

PICOmini™



SOT-563 CASE

* Device is *Halogen Free* by design

APPLICATIONS:

- Load/Power Switches
- Power Supply Converter Circuits
- Battery Powered Portable Equipment

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	8.0	V
Continuous Drain Current (Steady State)	I_D	860	mA
Continuous Drain Current, $t \leq 5.0\text{s}$	I_D	950	mA
Continuous Source Current (Body Diode)	I_S	360	mA
Maximum Pulsed Drain Current, $t_p = 10\mu\text{s}$	I_{DM}	4.0	A
Maximum Pulsed Source Current, $t_p = 10\mu\text{s}$	I_{SM}	4.0	A
Power Dissipation (Note 1)	P_D	350	mW
Power Dissipation (Note 2)	P_D	300	mW
Power Dissipation (Note 3)	P_D	150	mW
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W



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DESCRIPTION:

These CENTRAL SEMICONDUCTOR devices are Enhancement-mode P-Channel Field Effect Transistors, manufactured by the P-Channel DMOS Process, designed for high speed pulsed amplifier and driver applications. This MOSFET offers Low $r_{DS(on)}$ and Low Threshold Voltage.

MARKING CODES:

CMLDM8120: C81
CMLDM8120G*: C8G

FEATURES:

- Low $r_{DS(on)}$
- Low Threshold Voltage
- Logic Level Compatible
- Small SOT-563 package

SYMBOL		UNITS
V_{DS}	20	V
V_{GS}	8.0	V
I_D	860	mA
I_D	950	mA
I_S	360	mA
I_{DM}	4.0	A
I_{SM}	4.0	A
P_D	350	mW
P_D	300	mW
P_D	150	mW
T_J, T_{stg}	-65 to +150	°C
Θ_{JA}	357	°C/W

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_{GSSF}, I_{GSSR}	$V_{GS}=8.0\text{V}, V_{DS}=0$		1.0	50	nA
I_{DSS}	$V_{DS}=20\text{V}, V_{GS}=0$		5.0	500	nA
BV_{DSS}	$V_{GS}=0, I_D=250\mu\text{A}$	20	24		V
$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.45	0.76	1.0	V
V_{SD}	$V_{GS}=0\text{V}, I_S=360\text{mA}$			0.9	V
$r_{DS(ON)}$	$V_{GS}=4.5\text{V}, I_D=0.95\text{A}$		0.085	0.15	Ω
$r_{DS(ON)}$	$V_{GS}=4.5\text{V}, I_D=0.77\text{A}$		0.085	0.142	Ω
$r_{DS(ON)}$	$V_{GS}=2.5\text{V}, I_D=0.67\text{A}$		0.13	0.20	Ω
$r_{DS(ON)}$	$V_{GS}=1.8\text{V}, I_D=0.2\text{A}$		0.19	0.24	Ω
$Q_{g(tot)}$	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}, I_D=1.0\text{A}$		3.56		nC
Q_{gs}	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}, I_D=1.0\text{A}$		0.36		nC
Q_{gd}	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}, I_D=1.0\text{A}$		1.52		nC

Notes: (1) Ceramic or aluminum core PC Board with copper mounting pad area of 4.0mm^2

(2) FR-4 Epoxy PC Board with copper mounting pad area of 4.0mm^2

(3) FR-4 Epoxy PC Board with copper mounting pad area of 1.4mm^2

R4 (2-August 2011)

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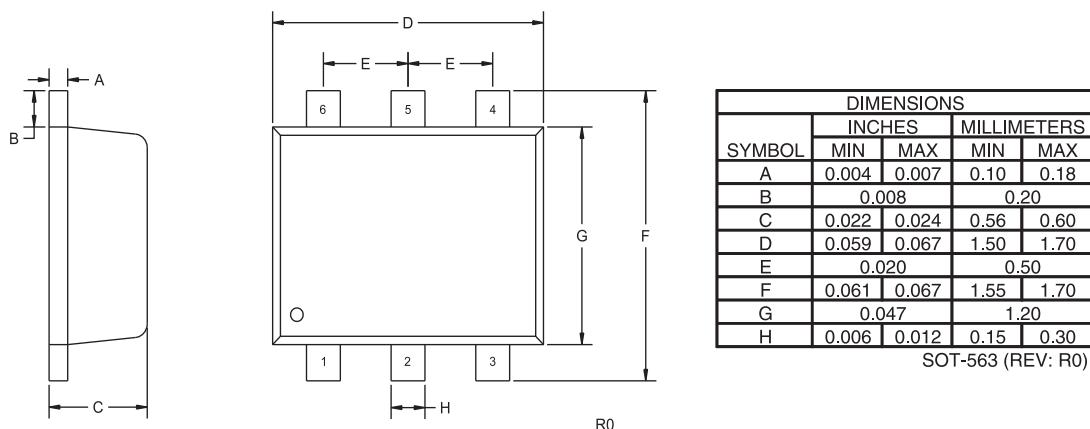
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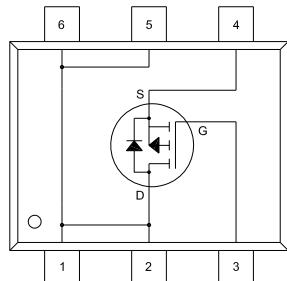
ELECTRICAL CHARACTERISTICS - Continued: ($T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
g_{FS}	$V_{DS}=10\text{V}$, $I_D=0.81\text{A}$	2.0			S
C_{rss}	$V_{DS}=16\text{V}$, $V_{GS}=0$, $f=1.0\text{MHz}$		80		pF
C_{iss}	$V_{DS}=16\text{V}$, $V_{GS}=0$, $f=1.0\text{MHz}$		200		pF
C_{oss}	$V_{DS}=16\text{V}$, $V_{GS}=0$, $f=1.0\text{MHz}$		60		pF
t_{on}	$V_{DD}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=0.95\text{A}$, $R_G=6\Omega$		20		ns
t_{off}	$V_{DD}=10\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=0.95\text{A}$, $R_G=6\Omega$		25		ns

SOT-563 CASE - MECHANICAL OUTLINE



PIN CONFIGURATION



LEAD CODE:

- 1) Drain
- 2) Drain
- 3) Gate
- 4) Source
- 5) Drain
- 6) Drain

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